

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1.-13. (Cancelled).

14. (Original) A method of fabricating a magnetic head cluster comprising the steps of:

providing a substrate;

forming at least two transducer elements on a surface of the substrate; and

forming at least one resistive element on the surface of the substrate between two of the at least two transducer elements.

15. (Original) A method of fabricating a magnetic head cluster in accordance with claim 14, further comprising the step lapping an edge portion of the magnetic head cluster.

16. (Original) A method of fabricating a magnetic head cluster in accordance with claim 15, further comprising the step of measuring the resistance of the at least one resistive element.

17. (Original) A method of fabricating a magnetic head cluster in accordance with claim 16, wherein the step of measuring the resistance is performed during the step of lapping, and wherein the step of lapping is performed until the resistance of at least one of the resistive elements reaches a specified resistance.

18. (Original) A method of fabricating a magnetic head cluster in accordance with claim 15, further comprising a plurality of resistive elements, and wherein each of the plurality of resistive elements is formed on the surface of the substrate between two of the at least two transducer elements.

19. (Original) A method of fabricating a magnetic head cluster in accordance with claim 18, further comprising the step of measuring the resistance of at least one of the plurality of resistive elements.

20. (Original) A method of fabricating a magnetic head cluster in accordance with claim 19, wherein the step of measuring the resistance is performed during the step of lapping, and wherein the step of lapping is performed until the resistance of at least one of the resistive elements reaches a predetermined resistance.

21. (Original) A method of fabricating a magnetic head cluster in accordance with claim 15, wherein at least one of the plurality of resistive elements is selected from a group consisting of analog switch lapping guides and digital switch lapping guides.